



Material Content Data Sheet



Sales Product Name				IPZ40N04S5L-7R4		Issued		30. July 2019	
MA#				MA001338260					
Package				PG-TSDSON-8-32		Weight*		35.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.222	0.63	0.63	6311	6311	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		353		
	non noble metal	iron	7439-89-6	0.249	0.71		7065		
wire	non noble metal	copper	7440-50-8	10.102	28.69	29.45	286878	294384	
	noble metal	gold	7440-57-5	0.031	0.09	0.09	876	876	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1065	
plastics	plastics	epoxy resin	-	1.931	5.48		54834		
	inorganic material	silicondioxide	60676-86-0	16.779	47.63	53.22	476471	532370	
	leadfinish	non noble metal	tin	7440-31-5	0.400	1.14	1.14	11367	11367
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2432	2432	
solder	non noble metal	tin	7440-31-5	0.007	0.02		210		
	noble metal	silver	7440-22-4	0.009	0.03		262		
	non noble metal	lead	7439-92-1	0.353	1.00	1.05	10013	10485	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
	non noble metal	iron	7439-89-6	0.073	0.21		2068		
heatspreader	non noble metal	copper	7440-50-8	2.958	8.40	8.62	83988	86185	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		67		
*deviation	non noble metal	iron	7439-89-6	0.047	0.13		1334		
	non noble metal	copper	7440-50-8	1.908	5.42	5.56	54172	55590	
						Sum in total:	100.00		1000000

Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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